

DATA SHEET

CBT3125 Quadruple FET bus switch

Product data

2001 Dec 12

File under Integrated Circuits — ICL03

Quadruple FET bus switch

CBT3125

DESCRIPTION

The CBT3125 quadruple FET bus switch features independent line switches. Each switch is disabled when the associated Output Enable (\overline{OE}) input is HIGH.

FEATURES

- Standard '125-type pinout (D, DB, and PW packages)
- 5 Ω switch connection between two ports
- TTL-compatible input levels
- Latch-up testing is done to JESDEC Standard JESD78 which exceeds 500 mA
- ESD protection exceeds 2000 V HBM per JESD22-A114, 200 V MM per JESD22-A115, and 1000 V CDM per JESD22-C101

PIN CONFIGURATION

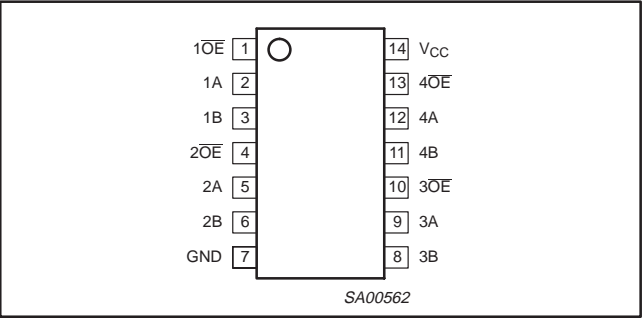
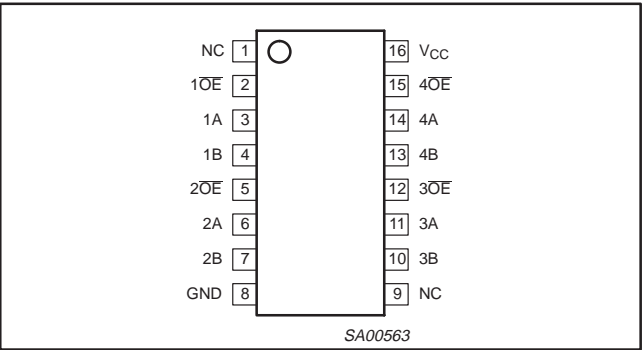


Figure 1. SO14, SSOP14, and TSSOP14



NC = no internal connection

Figure 2. SSOP(QSOP)16

ORDERING INFORMATION

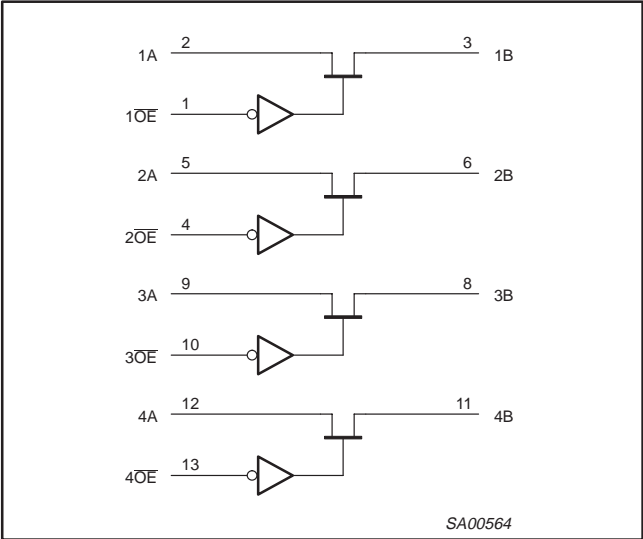
PACKAGES	TEMPERATURE RANGE	ORDER CODE	DRAWING NUMBER
14-Pin Plastic SO	−40 to +85 °C	CBT3125D	SOT108-1
14-Pin Plastic SSOP	−40 to +85 °C	CBT3125DB	SOT337-1
16-Pin Plastic SSOP(QSOP)	−40 to +85 °C	CBT3125DS	SOT519-1
14-Pin Plastic TSSOP	−40 to +85 °C	CBT3125PW	SOT402-1

Standard packing quantities and other packaging data is available at www.philipslogic.com/packaging.

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LOGIC DIAGRAM



Pin numbers shown are for 14-pin package-types.

Figure 3. CBT3125 logic diagram (positive logic)

FUNCTION TABLE (each bus switch)

INPUT OE	FUNCTION
L	A = B
H	disconnect

ABSOLUTE MAXIMUM RATINGS¹

Over operating free-air temperature range, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage range		−0.5	7	V
V _I	input voltage range	see Note 2	−0.5	7	V
	continuous channel current		—	128	mA
I _K	input clamp current	V _{I/O} < 0	—	−50	mA
T _{stg}	storage temperature range		−65	+150	°C

NOTES:

- Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS¹

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage		4.5	5.5	V
V _{IH}	high-level control input voltage		2	—	V
V _{IL}	low-level control input voltage		—	0.8	V
T _{amb}	operating ambient temperature in free-air		−40	+85	°C

NOTE:

- All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range, unless otherwise noted.

SYMBOL	PARAMETER		CONDITIONS	MIN.	TYP. ¹	MAX.	UNIT
V_{IK}	Input clamp voltage		$V_{CC} = 4.5\text{ V};$ $I_I = -18\text{ mA}$	—	—	-1.2	V
I_I	Input leakage current		$V_{CC} = 5.5\text{ V};$ $V_I = 5.5\text{ V or GND}$	—	—	± 1	μA
I_{CC}	Quiescent supply current		$V_{CC} = 5.5\text{ V}; I_O = 0;$ $V_I = V_{CC} \text{ or GND}$	—	—	3	μA
ΔI_{CC}	Additional supply current per input pin (Note 2)	control inputs	$V_{CC} = 5.5\text{ V};$ one input at 3.4 V, other inputs at V_{CC} or GND	—	—	2.5	mA
C_I	Input capacitance	control inputs	$V_I = 3\text{ V or 0}$	—	1.7	—	pF
$C_{IO(OFF)}$	Power-off leakage current		$V_O = 3\text{ V or 0}; \overline{OE} = V_{CC}$	—	3.4	—	pF
V_P	Pass gate voltage		$V_{CC} = 5.0\text{ V}; V_I = 5.0\text{ V}$	—	3.8	—	V
r_{on}	On-resistance (Note 3)		$V_{CC} = 4.5\text{ V}; V_I = 0\text{ V};$ $I_I = 64\text{ mA}$	—	5	7	Ω
			$V_{CC} = 4.5\text{ V}; V_I = 0\text{ V};$ $I_I = 30\text{ mA}$	—	5	7	Ω
			$V_{CC} = 4.5\text{ V}; V_I = 2.4\text{ V};$ $I_I = -15\text{ mA}$	—	10	15	Ω

NOTES:

1. All typical values are at $V_{CC} = 5\text{ V}$, unless otherwise noted. $T_{amb} = 25\text{ }^\circ\text{C}$.
2. This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.
3. Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

AC CHARACTERISTICS

$T_{amb} = -40\text{ to }+85\text{ }^\circ\text{C}$; $C_L = 50\text{ pF}$, unless otherwise noted.

SYMBOL	PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
				Min	Max	
t_{pd}	Propagation delay ¹	A or B	B or A	—	0.25	ns
t_{en}	Output enable time to High and Low level	\overline{OE}	A or B	1.0	5.4	ns
t_{dis}	Output disable time from High and Low level	\overline{OE}	A or B	1	4.7	ns

NOTE:

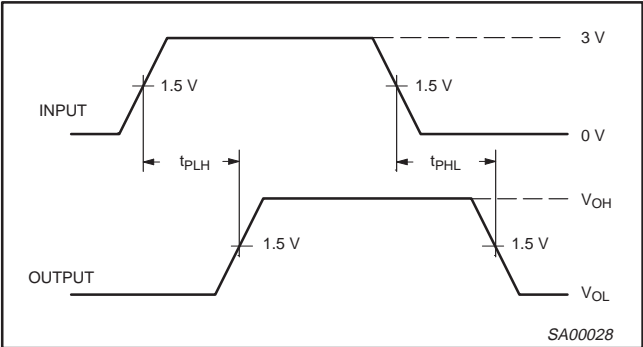
1. This parameter is warranted but not production tested. The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

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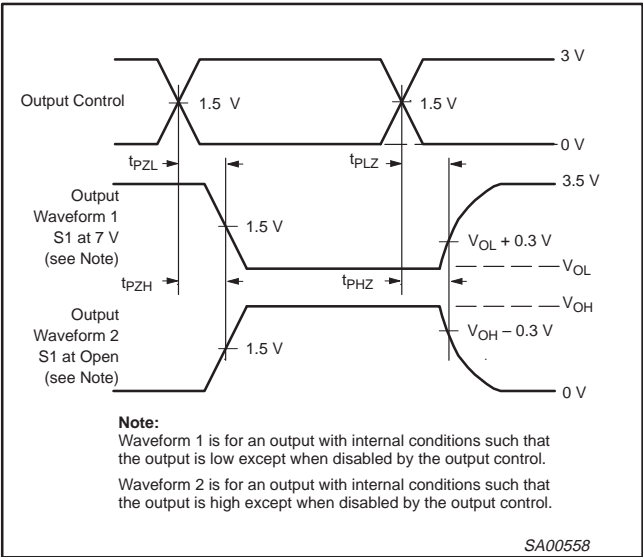
AC WAVEFORMS

$V_M = 1.5\text{ V}$, $V_{IN} = \text{GND to } 3.0\text{ V}$



t_{PLH} and t_{PHL} are the same as t_{pd} .

Waveform 1. Input to Output Propagation Delays



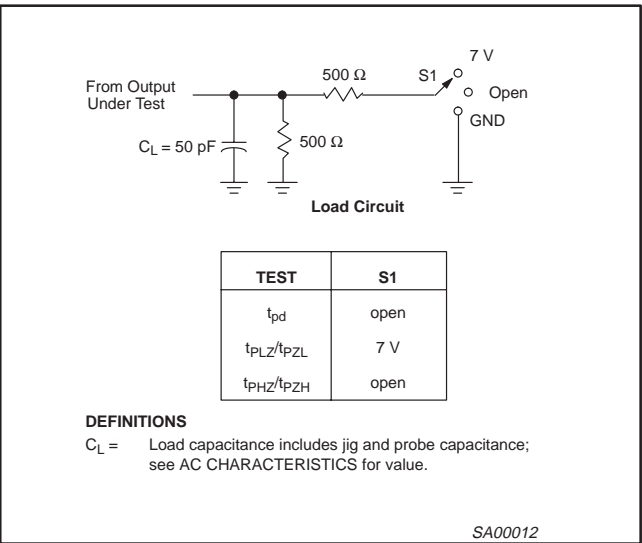
Note:
Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

t_{PLZ} and t_{PHZ} are the same as t_{dis} .

t_{PZL} and t_{PZH} are the same as t_{en} .

Waveform 2. Output Enable and Disable Times

TEST CIRCUIT



t_{PLZ} and t_{PHZ} are the same as t_{dis} .

t_{PZL} and t_{PZH} are the same as t_{en} .

NOTES:

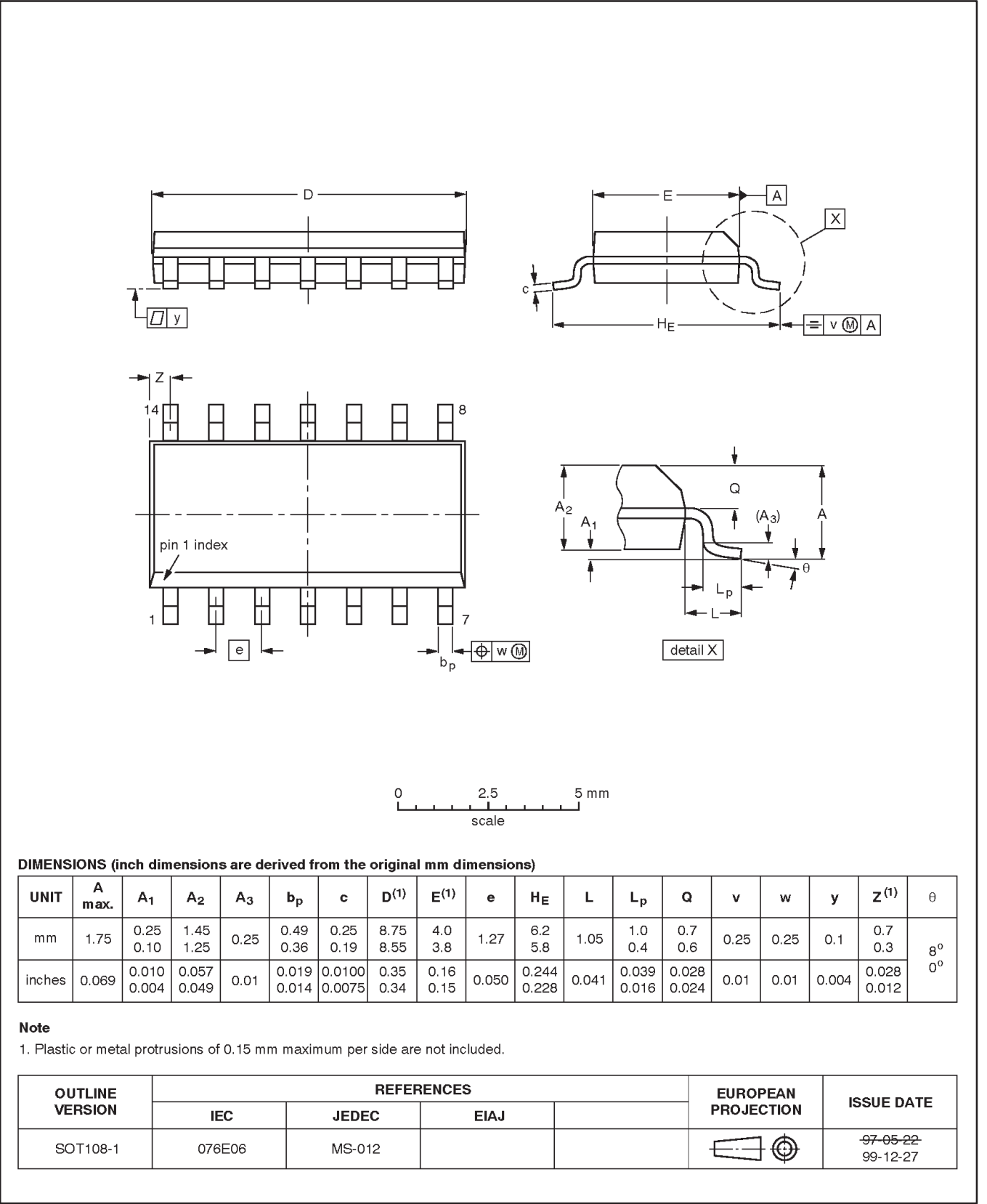
1. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
2. The outputs are measured one at a time with one transition per measurement.

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SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

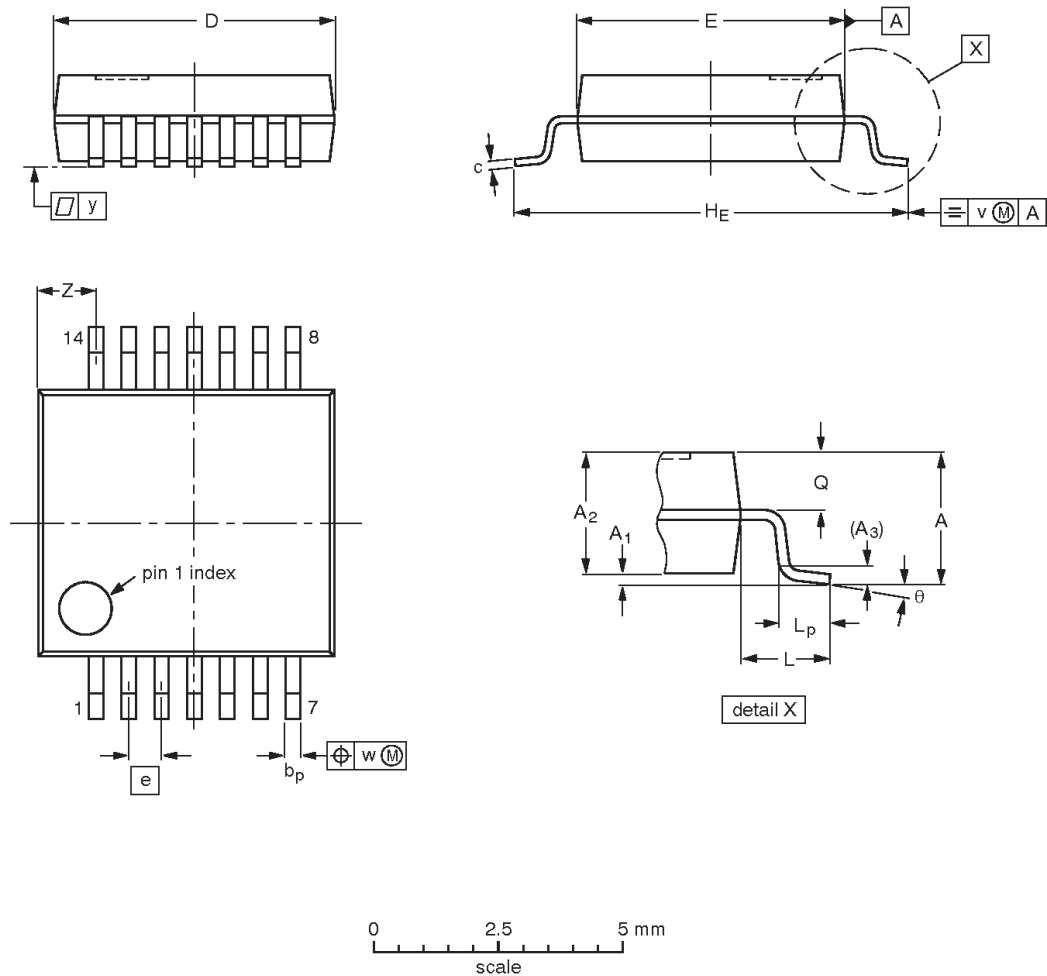


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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1




DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

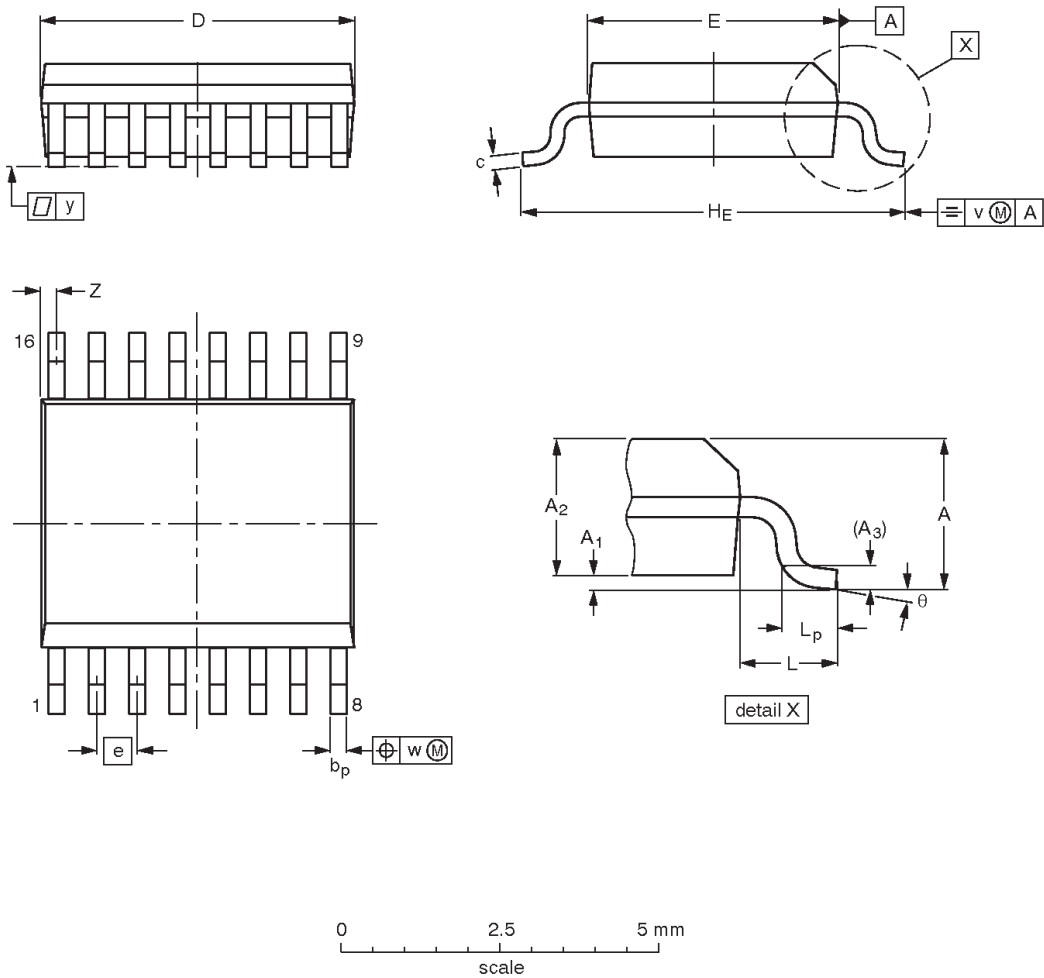
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT337-1		MO-150				96-01-18 99-12-27

Quadruple FET bus switch

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SSOP16: plastic shrink small outline package; 16 leads;
body width 3.9 mm; lead pitch 0.635 mm


SOT519-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
mm	1.73	0.25 0.10	1.55 1.40	0.25	0.31 0.20	0.25 0.18	5.0 4.8	4.0 3.8	0.635	6.2 5.8	1.0	0.89 0.41	0.2	0.18	0.09	0.18 0.05	8° 0°

Note
1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

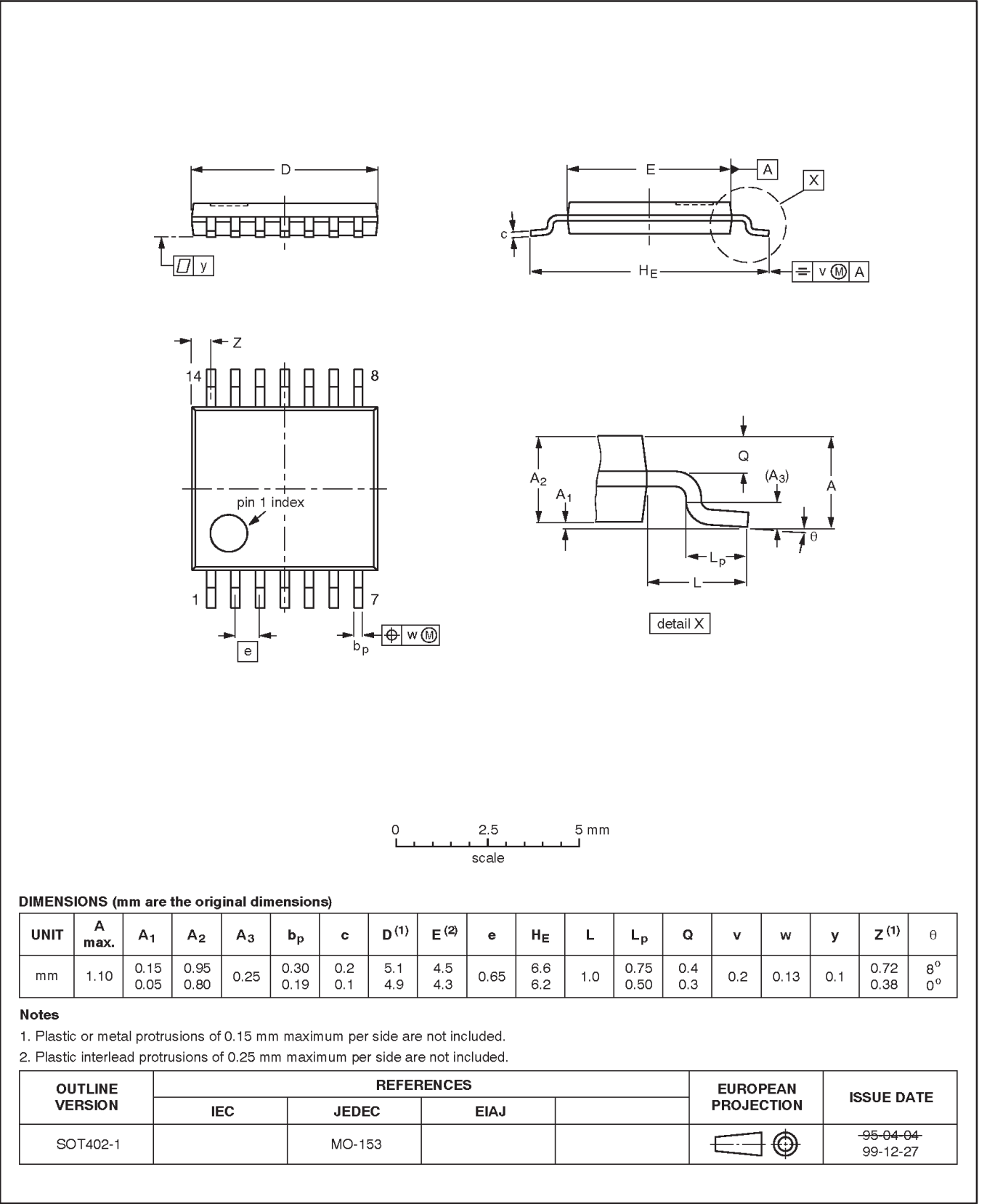
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT519-1						99-05-04

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TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



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Data sheet status

Data sheet status ^[1]	Product status ^[2]	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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